

WCNLB4-B711

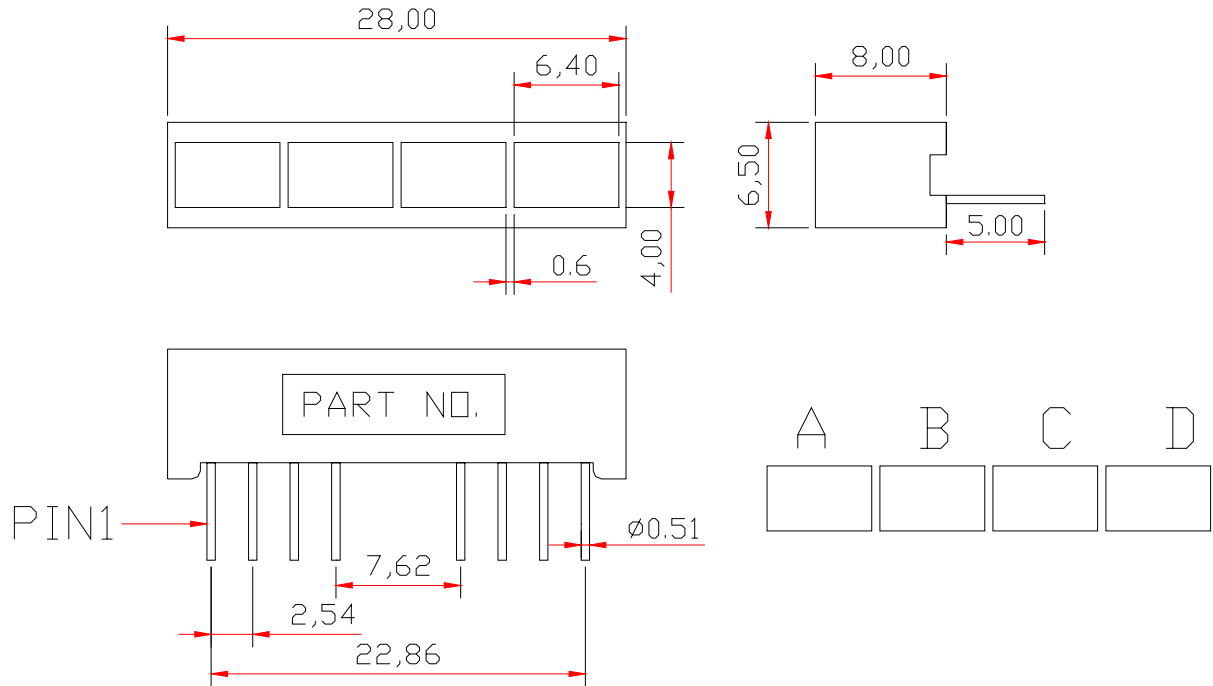
SPECIFICATION

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Fei 2016-8-5	Athena	William	
REVISION RECORD			



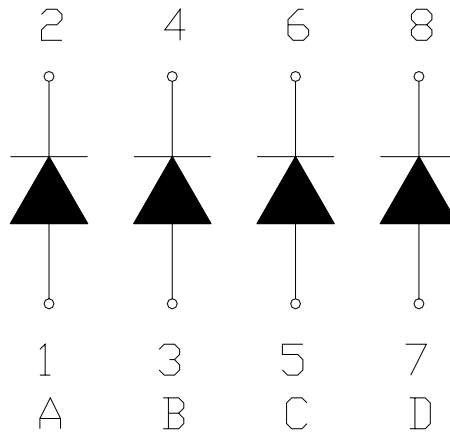
REVISION: A0

■ Outer Dimension:



Notes: Unless otherwise stated, The tolerance is ± 0.25 mm.

■ Circuit Diagram:



■ Pin Connection:

PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Anode A	5	Anode C
2	Cathode A	6	Cathode C
3	Anode B	7	Anode D
4	Cathode B	8	Cathode D

■ Features:

- High Reliability
- Color: Blue
- Low Power Requirement
- Easy Assembly

■ Description:

- Four Windows Display
- Digit Height 4.0mm(0.16") and Width 6.4mm(0.25")
- Black Face and Milky Bar

■ Absolute Maximum Rating (Ta=25°C):

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Bar	P _d	—	Blue	90	mW
Forward Current Per Bar	I _F	—	Blue	25	mA
Peak Forward Current Per Bar	I _{FP}	1/10 Duty 10KHz	Blue	100	mA
Reverse Voltage Per Bar	V _R	—	Blue	5	V
Operating Temperature Range	Topr	—	—	-35~+85	°C
Storage Temperature Range	Tstg	—	—	-35~+85	°C

■ Electrical/Optical Characteristics Rating(Ta=25°C)

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =20mA	Per Bar	—	3.2	3.60	V
Reverse Current	I _R	V _R =5V	Per Bar	—	—	100	μA
Luminous Intensity	I _V	I _F =10mA	Per Bar	15251	23500	37000	μcd
Wave Length	λ _P	I _F =20mA	Per Bar	—	—	—	nm
	λ _D				470		
Spectral Line Half Width	△λ	I _F =20mA	Per Bar	—	30	—	nm
Luminous Intensity Matching Ratio (Bar to Bar)	I _{v-m}	I _F =10mA				1.2:1	

■ Luminous Intensity Sorting: (Luminous Intensity Tolerance is +/-10%)

Rank	Symbol	Condition	Min	Max	Unit
S	S	I _F =10mA	15251	18000	μcd
T	T	I _F =10mA	18001	21500	μcd
U	U	I _F =10mA	21501	26000	μcd
V	V	I _F =10mA	26001	31000	μcd
W	W	I _F =10mA	31001	37000	μcd

■ Soldering Conditions: Soldering Temp. ≤ +260°C Soldering Time. ≤ 3sec.
(at 2mm Distance from The Case of Reflector Edge).

■ Typical Elector-Optical Characteristics Curve:

Fig1. Forward Current vs. Forward Voltage:

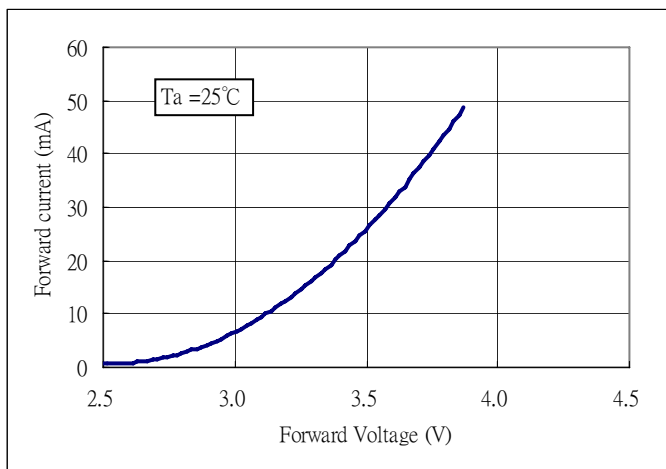


Fig2. Forward Current vs. Relative Intensity:

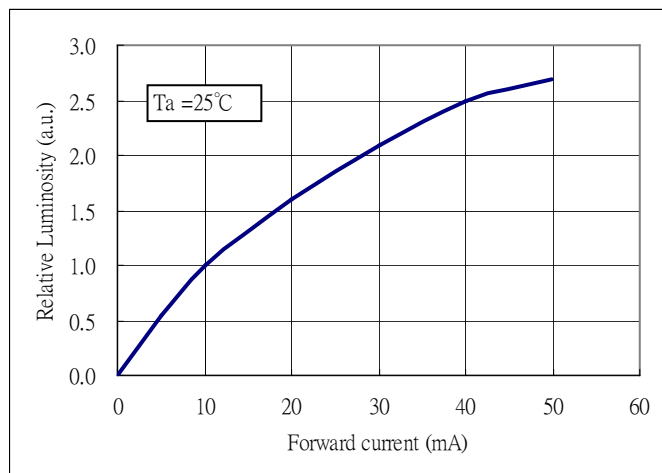


Fig3. Forward Current vs. Relative wavelength:

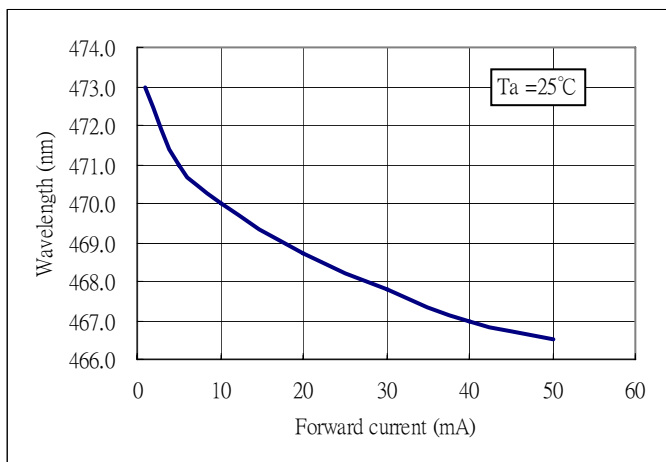
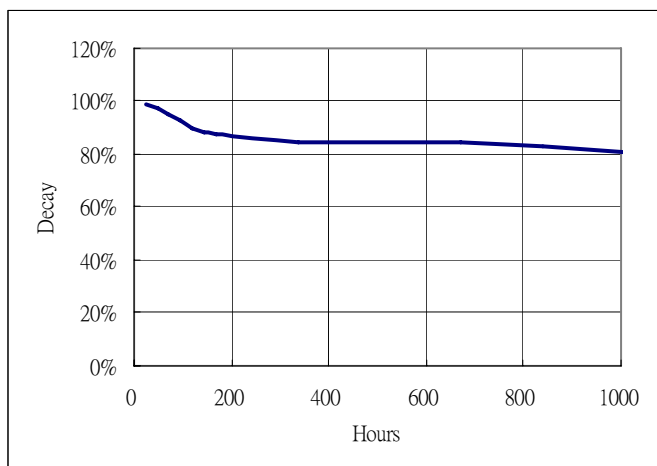


Fig4. Life Test at 20mA R.T. 1000hrs:



LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T _a = UNDER ROOM TEMPERATURE I _F = I _F max
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY T _a = 65±5°C RH=90~95%RH TEST TIME=240± 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE T _a = 85±5°C (COB: T _a =65±5°C) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE T _a = -35±5°C TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION 85°C ~ 25°C ~ -35°C ~ 25°C 30min 5min 30min 5min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES 85±5°C ~ -35±5°C 10min 10min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE T.SOL=230±5°C DWELL TIME=5±1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING T.SOL=260±5°C DWELL TIME=10±1sec.

Packing method :

250pcs / Red Expandable Polyethylene.

1500 pcs / Box(360*175*130mm).

9000 pcs / Catton(550*380*280mm).